

Title (en)

Device for and method of cutting with laser array

Title (de)

Vorrichtung und Verfahren zum Schneiden mit Laser-Array

Title (fr)

Dispositif et procédé de coupage par lasers en rangées

Publication

**EP 2727680 B1 20151230 (DE)**

Application

**EP 13187822 A 20131009**

Priority

DE 102012021723 A 20121105

Abstract (en)

[origin: EP2727680A1] The apparatus (10) has a transport device (5) for transporting a web or arcuate shaped substrate in a transport plane (E) in a transport direction (T). A laser cutting device (1) is arranged above or below the transport plane for processing the substrate, where a machine control unit (6) drives the transport device and the laser cutting device. The laser cutting device includes a laser array (2) having individually controllable vertical cavity surface emitting lasers extending across the width of the substrate. An independent claim is also included for a method for cutting and perforating a web or arcuate shaped substrate.

IPC 8 full level

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CPC (source: CN EP US)

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**B23K 26/38** (2013.01 - CN EP US); **B23K 26/382** (2015.10 - CN EP US); **B23K 37/0235** (2013.01 - CN EP US); **B23K 2103/38** (2018.07 - CN);  
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Designated contracting state (EPC)

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